

WHAT IS CLAIMED IS:

1. A lead frame, comprising:

a frame body made of a conductive material and including at least one opening for mounting a semiconductor chip;

a die pad placed in the opening of the frame body;

and

a group of leads extending from the frame body into the opening, the group of leads including at least:

a first lead connected to the frame body and including a first bonding pad provided on an upper surface of the first lead and a first land provided on a lower surface of the first lead;

a second lead connected to the frame body and including a second bonding pad provided on an upper surface of the second lead and a second land provided on a lower surface of the second lead; and

a third lead connected to the first lead and including a third bonding pad provided on an upper surface of the third lead and a third land provided on a lower surface of the third lead,

wherein a connecting portion that is thinner than the lead frame body and that can be punched through is provided between the first lead and the third lead.

2. The lead frame of claim 1, wherein at least the second lead includes a neck portion having a smaller width

than other portions as viewed in a plan view.

3. The lead frame of claim 1, wherein each lead includes a region around the bonding pad thereof that has a smaller thickness than that of a portion of the lead corresponding to the bonding pad, with a stepped portion being provided between the bonding pad and the region around the bonding pad.

4. The lead frame of claim 1, wherein the first, second and third lands are substantially coplanar on a common plane while being arranged in three rows on the common plane.

5. The lead frame of claim 1, wherein the second lead and a lead structure including the first and third leads are arranged alternately along a periphery of the opening of the frame body.

6. The lead frame of claim 1, wherein the frame body, the die pad and the group of leads are made of a single metal plate.